

National Institute of Standards & Technology

Certificate of Analysis

Standard Reference Material 395

Unalloyed Copper - Cu II

(In Cooperation with the American Society for Testing and Materials)

This Standard Reference Material (SRM) is in the form of small chips, sized between 0.5 mm and 1.4 mm sieve openings (35 - 14 mesh). The SRM is intended for use in trace analysis of copper materials. It is designed for all techniques applicable to compositional analysis of unalloyed copper and it is particularly well suited for calibration with optical emission methods of analysis. Material from the same original ingot, designated SRM 495, was processed in the form of rods 6.4 mm (1/4 in) in diameter.

<u>Element</u>	Certified Value ^a mg/kg	Estimated <u>Uncertainty</u> b	<u>Element</u>	Certified Value ^a <u>mg/kg</u>	Estimated <u>Uncertainty</u>
Antimonyc	8.0	0.5	Nickel ^d	5.4	0.1
Arsenic ^c	1.6	0.3	Selenium ^c	0.63	0.07
Bismuth ^c	0.50	0.10	Silver ^d	12.2	0.1
Chromium ^c	6.0	0.5	Sulfur ^c	13	1
Iron ^d	96	3	Tellurium ^c	0.32	0.01
Lead ^d	3.25	0.02	Tin ^c	1.5	0.2
Manganese ^c	5.3	0.8	Zinc ^c	12.2	0.7
	Certified				
	Value ^a	Estimated			
Element	_wt %*	<u>Uncertainty</u> ^b			
Copper ^c , assay	99.944	(0.008		

^{*}wt $\% = mg/kg \times 10^{-4}$

Gaithersburg, MD 20899 July 16, 1993 (Revision of certificate dated 10-9-87) Thomas E. Gills, Acting Chief Standard Reference Materials Program

^aThe value listed for an element is the *present best estimate* of the "true" value based on the results of the analytical program for certification. ^bThe estimated uncertainty listed for a constituent is based on judgment and represents an evaluation of the combined effects of method imprecision, possible systematic errors among methods, and material variability for samples of 0.25 g or more, used in the "as received" condition. (No attempt was made to derive exact statistical measures of imprecision because several methods were involved in the analysis of most constituents.)

^cValues are based on agreement of determinations at NIST and cooperating laboratories; values for Bi and S are based on agreement of determinations at cooperating laboratories.

^dValues are based on determinations at NIST by two or more of the following methods: atomic absorption and flame emission spectrometry, isotopic dilution mass spectrometry, neutron activation analysis, polarography, and spark source mass spectrometry.

This Certificate of Analysis has undergone editorial revision to reflect program and organizational changes at NIST and at the Department of Commerce. No attempt was made to reevaluate the certificate values or any technical data presented on this certificate.

The overall direction and coordination of the preparation and fabrication of this material were performed by J.G. Hust, M.B. Kasen, and R.P. Reed, NIST, Boulder, CO.

The overall coordination of the NIST analytical measurements leading to certification was under the direction of I.L. Barnes.

The technical and support aspects involved in the original certification and issuance of this SRM were coordinated through the Standard Reference Materials Program by R.E. Michaelis. Revision of this certificate was coordinated through the Standard Reference Materials Program by P.A. Lundberg.

PLANNING, PREPARATION, TESTING, ANALYSIS

This material is one in a series of twelve different composition copper "Benchmark" materials, Cu "O" through Cu XI, that were prepared in a cooperative Industry-ASTM-NIST Program.

Base material for the preparation of Cu II was supplied by U.S. Metals Refining Co., AMAX Copper Division, Carteret, NJ. Melting and casting were done at the Esco Corp., Portland, OR.

Preliminary results, primarily by optical emission methods of analysis, indicated a useful concentration level was present for most of the desired impurity elements and the ingot was accepted. The preliminary analyses were performed in the analytical laboratories of:

Anaconda Co., Primary Metals Division, Raritan Copper Works, Perth Amboy, NJ, P.F. Stryker and A.J. Simon.

Hecla Mining Co., Lakeshore Project, Casa Grande, AZ, N. Ciani.

Kennecott Copper Corp., Ledgemont Laboratory, Lexington, MA, F.D. Leipziger.

Kennecott Copper Corp., Kennecott Research Center, Salt Lake City, UT, A.P. Langheinrich.

Kennecott Copper Corp., Utah Copper Division, Refinery Plant, Magna, UT, N.N. Linde.

Kennecott Refining Corp., Baltimore, MD, A.A. DiLeonardi.

Magma Copper Co., San Manuel Division, San Manuel, AR, T.L. Young, and S.K. Young.

Phelps Dodge Refining Corp., El Paso Works, El Paso, TX, A.L. Cardinal.

U.S. Metals Refining Co., AMAX Copper Division, Carteret, NJ, R.M. Kennedy.

The ingot was processed by the U.S. Bureau of Mines, Albany, OR, R.A. Beall, to provide materials of the highest possible homogeneity, both in billet and rod forms. The ingot was approximately 24 cm (9 1/2 in) in diameter, 81 cm (32 in) long, weighing about 318 kg (700 lb). The ingot was forged to produce a bar 15 cm (6 in) square. Five percent of the total volume was cropped from the end of the bar representative of the bottom of the original ingot and fifteen percent from the top. The bar was then cut into equal lengths of approximately 46 cm (18 in) to form three billets. One billet, selected for the chip material, was end-milled at NIST. The lot of chips was sieved and blended.

Cooperative homogeneity studies were made at Kennecott Refining Corp., Baltimore, MD, by optical emission spectro-chemical analysis, A.A. DiLeonardi. Extensive homogeneity studies were made at NIST Boulder, CO by residual resistivity ratio measurements, J.G. Hust and at NIST Gaithersburg, MD, by chemical analyses (see listing below). The results indicated the maximum gross material variability to be less than 5%.

Cooperative chemical analyses for certification were made on composite samples in the following analytical laboratories:

Anaconda American Brass Co., Research and Technical Center, Waterbury, CN, J.T. McCrackan and V.M. Horrigan.

Anglo American Corp. of South Africa Limited, Johannesburg, Republic of South Africa, R. Murray-Smith.

Bridgeport Brass Co. Bridgeport, CN, A.W. Young.

Carpenter Technology Corp., Research and Development Center, Reading, PA, C.T. Polinko.

Council for Scientific and Industrial Research, National Physical Research Laboratory, Pretoria, Republic of South Africa, L.R.P. Butler, D.B. deVilliers, and J.H. Wepener.

International Nickel Co., of Canada, Ltd., J. Roy Gordon Research Laboratory, Sheridan Park, Mississauga, Ontario, Canada, St. J.H. Blakeley.

Kennecott Copper Corp., Ledgemont Laboratory, Lexington, MA, F.D. Leipziger.

Kennecott Copper Corp., Research Center, Salt Lake City, UT, A.P. Langheinrich.

Kennecott Copper Corp., Utah Copper Division, Refinery Plant, Magna, UT, N.N. Linde.

Kennecott Refining Corp., Baltimore, MD, A.A. DiLeonardi.

National Research Council of Canada, Division of Chemistry, Ottawa, Canada, D.S. Russell.

Phelps Dodge, Copper Products Co., Elizabeth, NJ, J.R. Conniff.

Phelps Dodge Refining Corp., El Paso Works, El Paso, TX, A.L. Cardinal.

Phelps Dodge Refining Corp., Laurel Hill Works, Maspeth, NY, W.D. Charles and R. Kretschmann.

Reverse Copper and Brass Inc., Rome, NY, S. Glessner.

Scovill, Metals Division, Waterbury, CN, E.D. Wade.

South African Bureau of Standards, Physical Chemistry Division, Pretoria, Republic of South Africa, H.P. Beyers and P.G. Odendaal.

Southwire Co., Copper Division, Carrollton, GA, G.S. Bowers.

Analyses were performed in the NIST Analytical Chemistry Division by the following: I.L. Barnes, D.A. Becker, R.K. Bell, R.W. Burke, B.I. Diamondstone, M.S. Epstein, E.L. Garner, T.E. Gills, J.W. Gramlich, E.F. Heald, L.A. Machlan, E.J. Maienthal, T.J. Murphy, P.J. Paulsen, L.J. Powell, T.C. Rains, T.A. Rush, and M.J. Seward.

SUPPLEMENTAL INFORMATION

Analysts should use this chip material in the "as received" condition.

Some surface oxidation (discoloration) is present on this chip material, but the amount is not analytically significant for the elements certified. The analyst should keep the container tightly capped when not in use.

Elements other than those certified may be present in this material as indicated below. These are *not certified* but are given as additional information on the composition.

Elements Detected	Information Value <u>µg/g</u>
Aluminum	(<2)
Cadmium	(0.4)
Gold	(0.13)
Magnesium	(<1)
Oxygen*	(435)
Silicon	(<2)
Elements Not Detected	
Calcium	(<0.3)
Titanium	(<0.3)

^{*}The value for oxygen on this chip material is subject to change because of surface oxidation.